

AMENDMENTS TO THE CLAIMS

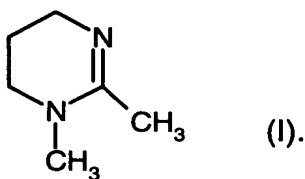
This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-12. (Cancelled)

Claim 13. (Currently Amended): A solventless reactive system, which is curable at room temperature and which comprises

- A) a polyisocyanate component comprising at least one organic polyisocyanate having a molecular weight, excluding the weight of the blocking agent, of 168 to 25,000 and in which at least 95 mole % of the NCO groups are reversibly blocked with at least one hydrocarbon resin containing phenolic OH groups and having a hydroxyl group content (calculated as OH, molecular weight 17) of 0.1% to 10.0%,
- B) at least one organic amine having at least 2 primary amino groups,
- C) an oxirane compound containing more than one epoxy group per molecule and
- D) a catalyst comprising 2,3-dimethyl-3,4,5,6-tetrahydropyrimidine of formula (I):



Claim 14. (Previously Presented): The solventless reactive system of Claim 13 wherein said organic polyisocyanate comprises an isocyanate group-containing prepolymer prepared by reacting (i) an aromatic polyisocyanate having a molecular weight of 174 to 300 and (ii) an ether and/or ester group-containing organic

polyhydroxyl compound having a molecular weight of 1000 to 8000, in which the isocyanate groups are reversibly blocked by reaction with at least one phenolic OH group-containing hydrocarbon resin having a hydroxyl group content (calculated as OH, molecular weight 17) of 0.1% to 10.0%.

Claim 15. (Previously Presented): The solventless reactive system of Claim 13 wherein the isocyanate groups of component A) are reversibly blocked by reaction with a hydrocarbon resin which contains phenolic OH groups, is liquid at room temperature and has a hydroxyl group content of 1.5% to 4.0%.

Claim 16. (Previously Presented): The solventless reactive system of Claim 14 wherein the isocyanate groups of component A) are reversibly blocked by reaction with a hydrocarbon resin which contains phenolic OH groups, is liquid at room temperature and has a hydroxyl group content of 1.5% to 4.0%.

Claim 17. (Previously Presented): The solventless reactive system of Claim 13 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 18. (Previously Presented): The solventless reactive system of Claim 14 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 19. (Previously Presented): The solventless reactive system of Claim 15 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 20. (Previously Presented): The solventless reactive system of Claim 16 wherein component B) comprises at least one diamine containing at least one cycloaliphatic ring and having a maximum molecular weight of 500.

Claim 21. (Previously Presented): The solventless reactive system of Claim 13 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 22. (Previously Presented): The solventless reactive system of Claim 14 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 23. (Previously Presented): The solventless reactive system of Claim 15 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 24. (Previously Presented): The solventless reactive system of Claim 16 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 25. (Previously Presented): The solventless reactive system of Claim 17 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 26. (Previously Presented): The solventless reactive system of Claim 18 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 27. (Previously Presented): The solventless reactive system of Claim 19 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 28. (Previously Presented): The solventless reactive system of Claim 20 wherein component C) comprises a liquid epoxy resin that is the reaction product of epichlorohydrin and 2,2-diphenylolpropane (bisphenol A) or diphenylolmethane (bisphenol F).

Claim 29. (Previously Presented): The solventless reactive system of Claim 13 wherein component D) is used in an amount of 0.5 to 3 wt.%, based on the weight of components A) and C).

Claim 30. (Previously Presented): The solventless reactive system of Claim 28 wherein component D) is used in an amount of 0.5 to 3 wt.%, based on the weight of components A) and C).

Claim 31. (Previously Presented): An adhesive, sealant, casting compound, molded article or coating prepared from the solventless reactive system of Claim 13.

Claim 32. (Previously Presented): A coating prepared from the solventless reactive system of Claim 13.